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# **Understanding Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

# **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	18480
Number of Logic Elements/Cells	49000
Total RAM Bits	3464192
Number of I/O	223
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	383-TFBGA
Supplier Device Package	383-MBGA (13x13)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5cefa4m13i7n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



# **Cyclone V Device Overview**

The Cyclone® V devices are designed to simultaneously accommodate the shrinking power consumption, cost, and time-to-market requirements; and the increasing bandwidth requirements for high-volume and cost-sensitive applications.

Enhanced with integrated transceivers and hard memory controllers, the Cyclone V devices are suitable for applications in the industrial, wireless and wireline, military, and automotive markets.

### **Related Information**

Cyclone V Device Handbook: Known Issues

Lists the planned updates to the Cyclone V Device Handbook chapters.

# **Key Advantages of Cyclone V Devices**

Table 1. Key Advantages of the Cyclone V Device Family

Advantage	Supporting Feature
Lower power consumption	Built on TSMC's 28 nm low-power (28LP) process technology and includes an abundance of hard intellectual property (IP) blocks     Up to 40% lower power consumption than the previous generation device
Improved logic integration and differentiation capabilities	8-input adaptive logic module (ALM)     Up to 13.59 megabits (Mb) of embedded memory     Variable-precision digital signal processing (DSP) blocks
Increased bandwidth capacity	3.125 gigabits per second (Gbps) and 6.144 Gbps transceivers     Hard memory controllers
Hard processor system (HPS) with integrated Arm* Cortex*-A9 MPCore* processor	<ul> <li>Tight integration of a dual-core Arm Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Cyclone V system-on-a-chip (SoC)</li> <li>Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric</li> </ul>
Lowest system cost	Requires only two core voltages to operate  Available in low-cost wirebond packaging  Includes innovative features such as Configuration via Protocol (CvP) and partial reconfiguration

### CV-51001 | 2018.05.07



Resource		Member Code						
		С3	C4	<b>C5</b>	С7	<b>C9</b>		
LVDS	Transmitter	52	84	84	120	140		
	Receiver	52	84	84	120	140		
PCIe Hard IP Block		1	2	2	2	2		
Hard Memory Controller		1	2	2	2	2		

### **Related Information**

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

# **Package Plan**

**Table 7.** Package Plan for Cyclone V GX Devices

Member Code	M3 (11)	801 mm)	M3 (13 i		M4 (15		U3 (15		U4 (19 i	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
C3	_	_	_	_	_	_	144	3	208	3
C4	129	4	175	6	_	_	_	_	224	6
C5	129	4	175	6	_	_	_	_	224	6
C7	_	_	_	_	240	3	_	_	240	6
C9	_	_	_	_	_	_	_	_	240	5

Member Code	F4 (23 i		F672 (27 mm)		F896 (31 mm)		F1152 (35 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
C3	208	3	_	_	_	_	_	_
C4	240	6	336	6	_	_	_	_
C5	240	6	336	6	_	_	_	_
C7	240	6	336	9	480	9	_	_
С9	224	6	336	9	480	12	560	12

# **Cyclone V GT**

This section provides the available options, maximum resource counts, and package plan for the Cyclone V GT devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

### **Related Information**

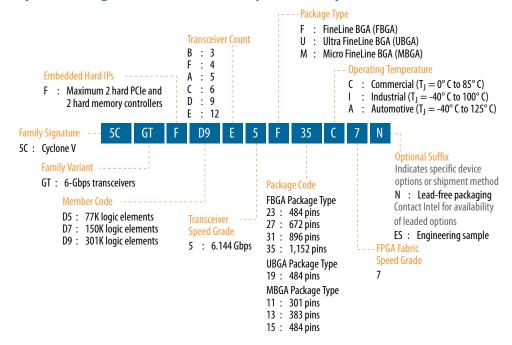
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# **Available Options**

Figure 3. Sample Ordering Code and Available Options for Cyclone V GT Devices



### **Maximum Resources**

**Table 8.** Maximum Resource Counts for Cyclone V GT Devices

Resource			Member Code				
		D5	D7	D9			
Logic Elements (LE) (	K)	77	150	301			
ALM		29,080	56,480	113,560			
Register		116,320	225,920	454,240			
Memory (Kb)	M10K	4,460	6,860	12,200			
	MLAB	424	836	1,717			
Variable-precision DS	P Block	150	156	342			
18 x 18 Multiplier		300	312	684			
PLL		6	7	8			
6 Gbps Transceiver		6	9	12			
GPIO <sup>(5)</sup>		336	480	560			
LVDS	Transmitter	84	120	140			
	,	•		continued			

<sup>(5)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.



# **Cyclone V SE**

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SE devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

#### **Related Information**

**Product Selector Guide** 

Provides the latest information about Intel products.

### **Available Options**

# Figure 4. Sample Ordering Code and Available Options for Cyclone V SE Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.





# **Cyclone V SX**

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

#### **Related Information**

#### **Product Selector Guide**

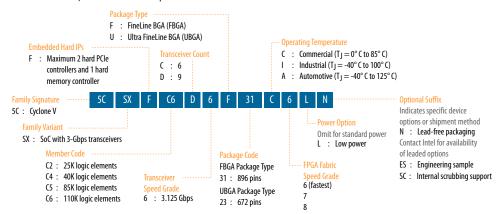
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### **Available Options**

# Figure 5. Sample Ordering Code and Available Options for Cyclone V SX Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.



#### **Maximum Resources**

**Table 12.** Maximum Resource Counts for Cyclone V SX Devices

Resource		Member Code						
		C2	C4	C5	C6			
Logic Elements (LE) (K)		25	40	85	110			
ALM		9,430	15,880	32,070	41,910			
Register		37,736	60,376	128,300	166,036			
Memory (Kb)	M10K	1,400	2,700	3,970	5,570			
	MLAB	138	231	480	621			
Variable-precision [	DSP Block	36	84	87	112			
18 x 18 Multiplier		72	168	174	224			
FPGA PLL		5	5	6	6			
					continued			



Resource			Member Code						
		C2	C4	C5	C6				
HPS PLL		3	3	3	3				
3 Gbps Transceiver		6	6	9	9				
FPGA GPIO (8)	FPGA GPIO <sup>(8)</sup>		145	288	288				
HPS I/O	HPS I/O		181	181	181				
LVDS	Transmitter	32	32	72	72				
	Receiver	37	37	72	72				
PCIe Hard IP Block		2	2	2 (9)	2 (9)				
FPGA Hard Memory	/ Controller	1	1	1	1				
HPS Hard Memory Controller		1	1	1	1				
Arm Cortex-A9 MP0	Core Processor	Dual-core	Dual-core	Dual-core	Dual-core				

### **Related Information**

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

### **Package Plan**

**Table 13.** Package Plan for Cyclone V SX Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U672 (23 mm)			F896 (31 mm)		
	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR
C2	145	181	6	_	_	_
C4	145	181	6	_	_	_
C5	145	181	6	288	181	9
C6	145	181	6	288	181	9

# **Cyclone V ST**

This section provides the available options, maximum resource counts, and package plan for the Cyclone V ST devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

<sup>(8)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>(9) 1</sup> PCIe Hard IP Block in U672 package.



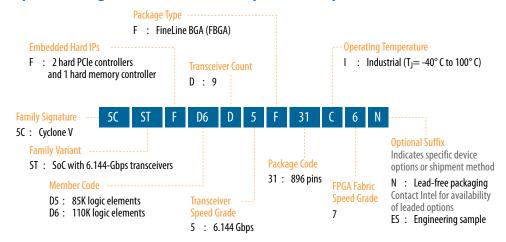
#### **Related Information**

#### **Product Selector Guide**

Provides the latest information about Intel products.

# **Available Options**

Figure 6. Sample Ordering Code and Available Options for Cyclone V ST Devices



# **Maximum Resources**

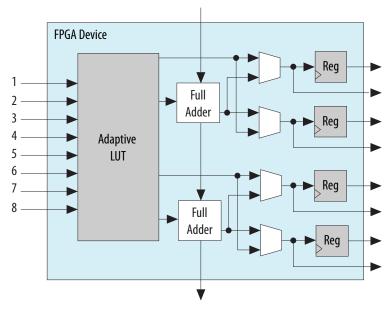
**Table 14.** Maximum Resource Counts for Cyclone V ST Devices

Reso	ource	Membe	r Code	
		D5	D6	
Logic Elements (LE) (K)		85	110	
ALM		32,070	41,910	
Register		128,300	166,036	
Memory (Kb)	M10K	3,970	5,570	
	MLAB	480	621	
Variable-precision DSP Block		87	112	
18 x 18 Multiplier		174	224	
FPGA PLL		6	6	
HPS PLL		3	3	
6.144 Gbps Transceiver		9	9	
FPGA GPIO <sup>(10)</sup>		288	288	
HPS I/O		181	181	
LVDS	Transmitter	72	72	
			continued	

<sup>(10)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.



Figure 8. ALM for Cyclone V Devices



You can configure up to 25% of the ALMs in the Cyclone V devices as distributed memory using MLABs.

#### **Related Information**

Embedded Memory Capacity in Cyclone V Devices on page 21 Lists the embedded memory capacity for each device.

# **Variable-Precision DSP Block**

Cyclone V devices feature a variable-precision DSP block that supports these features:

- Configurable to support signal processing precisions ranging from 9 x 9, 18 x 18 and 27 x 27 bits natively
- A 64-bit accumulator
- A hard preadder that is available in both 18- and 27-bit modes
- Cascaded output adders for efficient systolic finite impulse response (FIR) filters
- Internal coefficient register banks, 8 deep, for each multiplier in 18- or 27-bit mode
- Fully independent multiplier operation
- A second accumulator feedback register to accommodate complex multiplyaccumulate functions
- Fully independent Efficient support for single-precision floating point arithmetic
- The inferability of all modes by the Intel Quartus Prime design software



Table 16. Variable-Precision DSP Block Configurations for Cyclone V Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resource
Low precision fixed point for video applications	Three 9 x 9	1
Medium precision fixed point in FIR filters	Two 18 x 18	1
FIR filters and general DSP usage	Two 18 x 18 with accumulate	1
High precision fixed- or floating-point implementations	One 27 x 27 with accumulate	1

You can configure each DSP block during compilation as independent three 9  $\times$  9, two 18  $\times$  18, or one 27  $\times$  27 multipliers. With a dedicated 64 bit cascade bus, you can cascade multiple variable-precision DSP blocks to implement even higher precision DSP functions efficiently.

**Table 17.** Number of Multipliers in Cyclone V Devices

The table lists the variable-precision DSP resources by bit precision for each Cyclone V device.

Variant	Member Code	Variable- precision DSP Block		dent Input and plications Ope	18 x 18 Multiplier Adder Mode	18 x 18 Multiplier Adder	
		DSP Block	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	Adder Mode	Summed with 36 bit Input
Cyclone V E	A2	25	75	50	25	25	25
	A4	66	198	132	66	66	66
	A5	150	450	300	150	150	150
	A7	156	468	312	156	156	156
	A9	342	1,026	684	342	342	342
Cyclone V	C3	57	171	114	57	57	57
GX	C4	70	210	140	70	70	70
	C5	150	450	300	150	150	150
	C7	156	468	312	156	156	156
	C9	342	1,026	684	342	342	342
Cyclone V GT	D5	150	450	300	150	150	150
	D7	156	468	312	156	156	156
	D9	342	1,026	684	342	342	342
Cyclone V SE	A2	36	108	72	36	36	36
	A4	84	252	168	84	84	84
	A5	87	261	174	87	87	87
	A6	112	336	224	112	112	112
Cyclone V SX	C2	36	108	72	36	36	36
	C4	84	252	168	84	84	84
	C5	87	261	174	87	87	87
							continued



Variant	Member Variable- code precision		•	dent Input and plications Ope	18 x 18 Multiplier	18 x 18 Multiplier	
		DSP Block	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	Adder Mode	Adder Summed with 36 bit Input
	C6	112	336	224	112	112	112
Cyclone V ST	D5	87	261	174	87	87	87
	D6	112	336	224	112	112	112

# **Embedded Memory Blocks**

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.

# **Types of Embedded Memory**

The Cyclone V devices contain two types of memory blocks:

- 10 Kb M10K blocks—blocks of dedicated memory resources. The M10K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Cyclone V devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

# **Embedded Memory Capacity in Cyclone V Devices**

Table 18. Embedded Memory Capacity and Distribution in Cyclone V Devices

	Member	M1	M10K		MLAB		
Variant	Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Total RAM Bit (Kb)	
Cyclone V E	A2	176	1,760	314	196	1,956	
	A4	308	3,080	485	303	3,383	
	A5	446	4,460	679	424	4,884	
	A7	686	6,860	1338	836	7,696	
	A9	1,220	12,200	2748	1,717	13,917	
Cyclone V GX	C3	135	1,350	291	182	1,532	
	C4	250	2,500	678	424	2,924	
	C5	446	4,460	678	424	4,884	
	C7	686	6,860	1338	836	7,696	
	C9	1,220	12,200	2748	1,717	13,917	
continued							



#### **PLL Features**

The PLLs in the Cyclone V devices support the following features:

- Frequency synthesis
- On-chip clock deskew
- Jitter attenuation
- Programmable output clock duty cycles
- PLL cascading
- Reference clock switchover
- Programmable bandwidth
- User-mode reconfiguration of PLLs
- Low power mode for each fractional PLL
- Dynamic phase shift
- Direct, source synchronous, zero delay buffer, external feedback, and LVDS compensation modes

#### **Fractional PLL**

In addition to integer PLLs, the Cyclone V devices use a fractional PLL architecture. The devices have up to eight PLLs, each with nine output counters. You can use the output counters to reduce PLL usage in two ways:

- Reduce the number of oscillators that are required on your board by using fractional PLLs
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

If you use the fractional PLL mode, you can use the PLLs for precision fractional-N frequency synthesis—removing the need for off-chip reference clock sources in your design.

The transceiver fractional PLLs that are not used by the transceiver I/Os can be used as general purpose fractional PLLs by the FPGA fabric.

# FPGA General Purpose I/O

Cyclone V devices offer highly configurable GPIOs. The following list describes the features of the GPIOs:

- Programmable bus hold and weak pull-up
- $\bullet$  LVDS output buffer with programmable differential output voltage (V $_{\text{OD}}$  ) and programmable pre-emphasis
- ullet On-chip parallel termination (R<sub>T</sub> OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture



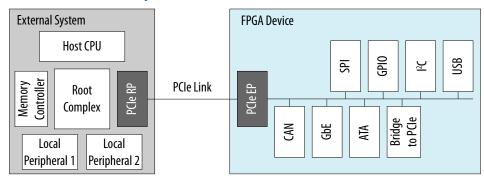
# PCIe Gen1 and Gen2 Hard IP

Cyclone V GX, GT, SX, and ST devices contain PCIe hard IP that is designed for performance and ease-of-use. The PCIe hard IP consists of the MAC, data link, and transaction layers.

The PCIe hard IP supports PCIe Gen2 and Gen1 end point and root port for up to x4 lane configuration. The PCIe Gen2 x4 support is PCIe-compatible.

The PCIe endpoint support includes multifunction support for up to eight functions, as shown in the following figure. The integrated multifunction support reduces the FPGA logic requirements by up to 20,000 LEs for PCIe designs that require multiple peripherals.

Figure 9. PCIe Multifunction for Cyclone V Devices



The Cyclone V PCIe hard IP operates independently from the core logic. This independent operation allows the PCIe link to wake up and complete link training in less than 100 ms while the Cyclone V device completes loading the programming file for the rest of the device.

In addition, the PCIe hard IP in the Cyclone V device provides improved end-to-end datapath protection using ECC.

# **External Memory Interface**

This section provides an overview of the external memory interface in Cyclone V devices.

# **Hard and Soft Memory Controllers**

Cyclone V devices support up to two hard memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices. Each controller supports 8 to 32 bit components of up to 4 gigabits (Gb) in density with two chip selects and optional ECC. For the Cyclone V SoC devices, an additional hard memory controller in the HPS supports DDR3, DDR2, and LPDDR2 SDRAM devices.

All Cyclone V devices support soft memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices for maximum flexibility.



# **External Memory Performance**

# Table 20. External Memory Interface Performance in Cyclone V Devices

The maximum and minimum operating frequencies depend on the memory interface standards and the supported delay-locked loop (DLL) frequency listed in the device datasheet.

Interface	Voltage	Maximum Fre	quency (MHz)	Minimum Frequency
	(V)	Hard Controller	Soft Controller	(MHz)
DDR3 SDRAM	1.5	400	303	303
	1.35	400	303	303
DDR2 SDRAM	1.8	400	300	167
LPDDR2 SDRAM	1.2	333	300	167

#### **Related Information**

### External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

# **HPS External Memory Performance**

### **Table 21. HPS External Memory Interface Performance**

The hard processor system (HPS) is available in Cyclone V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	400
	1.35	400
DDR2 SDRAM	1.8	400
LPDDR2 SDRAM	1.2	333

#### **Related Information**

# External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

# **Low-Power Serial Transceivers**

Cyclone V devices deliver the industry's lowest power 6.144 Gbps transceivers at an estimated 88 mW maximum power consumption per channel. Cyclone V transceivers are designed to be compliant with a wide range of protocols and data rates.

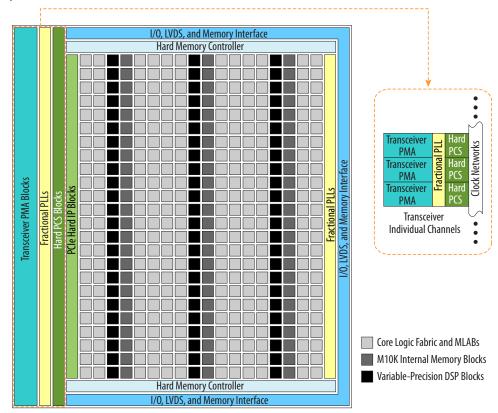
# **Transceiver Channels**

The transceivers are positioned on the left outer edge of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.



Figure 10. Device Chip Overview for Cyclone V GX and GT Devices

The figure shows a Cyclone V FPGA with transceivers. Different Cyclone V devices may have a different floorplans than the one shown here.



# **PMA Features**

To prevent core and I/O noise from coupling into the transceivers, the PMA block is isolated from the rest of the chip—ensuring optimal signal integrity. For the transceivers, you can use the channel PLL of an unused receiver PMA as an additional transmit PLL.

Table 22. PMA Features of the Transceivers in Cyclone V Devices

Features	Capability
Backplane support	Driving capability up to 6.144 Gbps
PLL-based clock recovery	Superior jitter tolerance
Programmable deserialization and word alignment	Flexible deserialization width and configurable word alignment pattern
Equalization and pre-emphasis	<ul> <li>Up to 14.37 dB of pre-emphasis and up to 4.7 dB of equalization</li> <li>No decision feedback equalizer (DFE)</li> </ul>
Ring oscillator transmit PLLs	614 Mbps to 6.144 Gbps
Input reference clock range	20 MHz to 400 MHz
Transceiver dynamic reconfiguration	Allows the reconfiguration of a single channel without affecting the operation of other channels



### **PCS Features**

The Cyclone V core logic connects to the PCS through an 8, 10, 16, 20, 32, or 40 bit interface, depending on the transceiver data rate and protocol. Cyclone V devices contain PCS hard IP to support PCIe Gen1 and Gen2, Gbps Ethernet (GbE), Serial RapidIO<sup>®</sup> (SRIO), and Common Public Radio Interface (CPRI).

Most of the standard and proprietary protocols from 614 Mbps to 6.144 Gbps are supported.

**Table 23.** Transceiver PCS Features for Cyclone V Devices

PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
3-Gbps and 6-Gbps Basic	0.614 to 6.144	<ul> <li>Phase compensation FIFO</li> <li>Byte serializer</li> <li>8B/10B encoder</li> <li>Transmitter bit-slip</li> </ul>	<ul> <li>Word aligner</li> <li>Deskew FIFO</li> <li>Rate-match FIFO</li> <li>8B/10B decoder</li> <li>Byte deserializer</li> <li>Byte ordering</li> <li>Receiver phase compensation FIFO</li> </ul>
PCIe Gen1 (x1, x2, x4)	2.5 and 5.0	Dedicated PCIe PHY IP core     PIPE 2.0 interface to the core logic	Dedicated PCIe PHY IP core     PIPE 2.0 interface to the core logic
PCIe Gen2 ( x1, x2, x4) <sup>(12)</sup>		logic	logic
GbE	1.25	Custom PHY IP core with preset feature     GbE transmitter synchronization state machine	Custom PHY IP core with preset feature     GbE receiver synchronization state machine
XAUI (13)	3.125	Dedicated XAUI PHY IP core	Dedicated XAUI PHY IP core
HiGig	3.75	XAUI synchronization state machine for bonding four channels	XAUI synchronization state machine for realigning four channels
SRIO 1.3 and 2.1	1.25 to 3.125	Custom PHY IP core with preset feature     SRIO version 2.1-compliant x2 and x4 channel bonding	Custom PHY IP core with preset feature     SRIO version 2.1-compliant x2 and x4 deskew state machine
SDI, SD/HD, and 3G-SDI	0.27 <sup>(14)</sup> , 1.485, and 2.97	Custom PHY IP core with preset feature	Custom PHY IP core with preset feature
JESD204A	0.3125 <sup>(15)</sup> to 3.125		
	,		continued

<sup>(12)</sup> PCIe Gen2 is supported for Cyclone V GT and ST devices. The PCIe Gen2 x4 support is PCIe-compatible.

<sup>(13)</sup> XAUI is supported through the soft PCS.

 $<sup>^{(14)}</sup>$  The 0.27-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

<sup>(15)</sup> The 0.3125-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.



Figure 11. HPS with Dual-Core Arm Cortex-A9 MPCore Processor



# **System Peripherals and Debug Access Port**

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals to interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports Arm CoreSight debug and core traces to facilitate software development.



Apart from lowering cost and power consumption, partial reconfiguration increases the effective logic density of the device because placing device functions that do not operate simultaneously is not necessary. Instead, you can store these functions in external memory and load them whenever the functions are required. This capability reduces the size of the device because it allows multiple applications on a single device—saving the board space and reducing the power consumption.

Intel simplifies the time-intensive task of partial reconfiguration by building this capability on top of the proven incremental compile and design flow in the Intel Quartus Prime design software. With the Intel solution, you do not need to know all the intricate device architecture details to perform a partial reconfiguration.

Partial reconfiguration is supported through the FPP x16 configuration interface. You can seamlessly use partial reconfiguration in tandem with dynamic reconfiguration to enable simultaneous partial reconfiguration of both the device core and transceivers.

# **Enhanced Configuration and Configuration via Protocol**

Cyclone V devices support  $1.8\ V$ ,  $2.5\ V$ ,  $3.0\ V$ , and  $3.3\ V$  programming voltages and several configuration schemes.

Table 24. Configuration Schemes and Features Supported by Cyclone V Devices

Mode	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps)	Decompressi on	Design Security	Partial Reconfigurat ion <sup>(18)</sup>	Remote System Update
AS through the EPCS and EPCQ serial configuration device	1 bit, 4 bits	100	_	Yes	Yes	_	Yes
PS through CPLD or external microcontroller	1 bit	125	125	Yes	Yes	_	_
FPP	8 bits	125	_	Yes	Yes	_	Parallel flash
	16 bits	125	_	Yes	Yes	Yes	loader
CvP (PCIe)	x1, x2, and x4 lanes	_	_	Yes	Yes	Yes	_
JTAG	1 bit	33	33	_	_	_	_

Instead of using an external flash or ROM, you can configure the Cyclone V devices through PCIe using CvP. The CvP mode offers the fastest configuration rate and flexibility with the easy-to-use PCIe hard IP block interface. The Cyclone V CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

# **Related Information**

Configuration via Protocol (CvP) Implementation in Intel FPGAs User Guide Provides more information about CvP.

<sup>(18)</sup> The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Date	Version	Changes
		<ul> <li>Updated MLAB RAM Bit (Kb) in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows:         <ul> <li>Cyclone V GX C3: Updated from 181 to 182</li> <li>Cyclone V GX C4: Updated from 295 to 424</li> </ul> </li> <li>Updated Total RAM Bit (Kb) in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows:         <ul> <li>Cyclone V GX C3: Updated from 1,531 to 1,532</li> <li>Cyclone V GX C4: Updated from 2,795 to 2,924</li> </ul> </li> <li>Updated MLAB Block count in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows:         <ul> <li>Cyclone V GX C4: Updated from 472 to 678</li> <li>Cyclone V GX C5: Updated from 679 to 678</li> </ul> </li> </ul>
March 2015	2015.03.31	Added internal scrubbing feature under configuration in Summary of Features for Cyclone V Devices table.     Added optional suffix "SC: Internal scrubbing support" to the following diagrams:     — Sample Ordering Code and Available Options for Cyclone V E Devices     — Sample Ordering Code and Available Options for Cyclone V GX Devices     — Sample Ordering Code and Available Options for Cyclone V SE Devices     — Sample Ordering Code and Available Options for Cyclone V SX Devices
January 2015	2015.01.23	<ul> <li>Updated Sample Ordering Code and Available Options for Cyclone V ST Devices figure because Cyclone V ST devices are only available in I temperature grade and -7 speed grade.</li> <li>Operating Temperature: Removed C and A temperature grades</li> <li>FPGA Fabric Speed Grade: Removed -6 and -8 speed grades</li> <li>Updated the transceiver specification for Cyclone V ST from 5 Gbps to 6.144 Gbps:</li> <li>Device Variants for the Cyclone V Device Family table</li> <li>Sample Ordering Code and Available Options for Cyclone V ST Devices figure</li> <li>Maximum Resource Counts for Cyclone V ST Devices</li> <li>Updated Maximum Resource Counts for Cyclone V GX Devices table for Cyclone V GX G3 devices.</li> <li>Logic elements (LE) (K): Updated from 35.7 to 35.5</li> <li>Variable-precision DSP block: Updated from 51 to 57</li> <li>18 x 18 multiplier: Updated from 102 to 114</li> <li>Updated Number of Multipliers in Cyclone V Devices table for Cyclone V GX G3 devices.</li> <li>Variableprecision DSP Block: Updated from 51 to 57</li> <li>9 x 9 Multiplier: Updated from 153 to 171</li> <li>18 x 18 Multiplier: Updated from 102 to 114</li> <li>27 x 27 Multiplier: Updated from 51 to 57</li> <li>18 x 18 Multiplier Adder Mode: Updated from 51 to 57</li> <li>18 x 18 Multiplier Adder Summed with 36 bit Input: Updated from 51 to 57</li> <li>Updated Embedded Memory Capacity and Distribution in Cyclone V Devices table for Cyclone V GX G3 devices.</li> <li>M10K Block: Updated from 119 to 135</li> <li>M10K RAM bit (Kb): Updated from 1,190 to 1,350</li> <li>MLAB BAM bit (Kb): Updated from 159 to 181</li> <li>Total RAM bit (Kb): Updated from 1,349 to 1,531</li> </ul>
October 2014	2014.10.06	Added a footnote to the "Transceiver PCS Features for Cyclone V Devices" table to show that PCIe Gen2 is supported for Cyclone V GT and ST devices.
		continued



Date	Version	Changes
		<ul> <li>Updated HPS I/O for U484 (19 mm) in Table 11 with '151' for A2, A4, A5 and A6.</li> <li>Updated Memory (Kb) for Maximum Resource Counts for Cyclone V SE A4 and A6, SX C4 and C6, ST D6 devices.</li> <li>Updated FPGA PLL for Maximum Resource Counts for Cyclone V SE A2, SX C2, devices.</li> <li>Removed '36 x 36' from the Variable-Precision DSP Block.</li> <li>Updated Variable-precision DSP Blocks and 18 x 18 Multiplier for Maximum Resource Counts for Cyclone V SX C4 device.</li> <li>Updated the HPS I/O counts for Cyclone V SE, SX, and ST devices.</li> <li>Updated Figure 7 which shows the I/O vertical migration table.</li> <li>Updated Table 17 for Cyclone V SX C4 device.</li> <li>Updated Embedded Memory Capacity and Distribution table for Cyclone V SE A4 and A6, SX C4 and C6, ST D6 devices.</li> <li>Removed 'Counter reconfiguration' from the PLL Features.</li> <li>Updated Low-Power Serial Transceivers by replacing 5 Gbps with 6.144 Gbps.</li> <li>Removed 'Distributed Memory' symbol.</li> <li>Updated the Capability in Table 22 of Backplane support to '6.144 Gbps'.</li> <li>Updated the PCS Support in Table 23 from 5 Gbps to '6 Gbps'.</li> <li>Updated the Data Rates (Gbps) in Table 23 of 3 Gbps and 6 Gbps Basic to '6.144 Gbps'.</li> <li>Updated the Data Rates (Gbps) in Table 23 of CPRI 4.1 to '6.144 Gbps'.</li> <li>Clarified that partial reconfiguration is an advanced feature. Contact Altera for support of the feature.</li> </ul>
December 2012	2012.12.28	<ul> <li>Updated the pin counts for the MBGA packages.</li> <li>Updated the GPIO and transceiver counts for the MBGA packages.</li> <li>Updated the GPIO counts for the U484 package of the Cyclone V E A9, GX C9, and GT D9 devices.</li> <li>Updated the vertical migration table for vertical migration of the U484 packages.</li> <li>Updated the MLAB supported programmable widths at 32 bits depth.</li> </ul>
November 2012	2012.11.19	<ul> <li>Added new MBGA packages and additional U484 packages for Cyclone V E, GX, and GT.</li> <li>Added ordering code for five-transceiver devices for Cyclone V GT and ST.</li> <li>Updated the vertical migration table to add MBGA packages.</li> <li>Added performance information for HPS memory controller.</li> <li>Removed DDR3U support.</li> <li>Updated Cyclone V ST speed grade information.</li> <li>Added information on maximum transceiver channel usage restrictions for PCI Gen2 and CPRI at 4.9152 Gbps transmit jitter compliance.</li> <li>Added note on the differences between GPIO reported in Overview with User I/O numbers shown in the Quartus II software.</li> <li>Updated template.</li> </ul>
July 2012	2.1	Added support for PCIe Gen2 x4 lane configuration (PCIe-compatible)
June 2012	2.0	<ul> <li>Restructured the document.</li> <li>Added the "Embedded Memory Capacity" and "Embedded Memory Configurations" sections.</li> <li>Added Table 1, Table 3, Table 16, Table 19, and Table 20.</li> <li>Updated Table 2, Table 4, Table 5, Table 6, Table 7, Table 8, Table 9, Table 10, Table 11, Table 12, Table 13, Table 14, Table 17, and Table 18.</li> </ul>

# CV-51001 | 2018.05.07



Date	Version	Changes
		<ul> <li>Updated Figure 1, Figure 2, Figure 3, Figure 4, Figure 5, Figure 6, and Figure 10.</li> <li>Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections.</li> <li>Text edits throughout the document.</li> </ul>
February 2012	1.2	<ul> <li>Updated Table 1-2, Table 1-3, and Table 1-6.</li> <li>Updated "Cyclone V Family Plan" on page 1-4 and "Clock Networks and PLL Clock Sources" on page 1-15.</li> <li>Updated Figure 1-1 and Figure 1-6.</li> </ul>
November 2011	1.1	<ul> <li>Updated Table 1-1, Table 1-2, Table 1-3, Table 1-4, Table 1-5, and Table 1-6.</li> <li>Updated Figure 1-4, Figure 1-5, Figure 1-6, Figure 1-7, and Figure 1-8.</li> <li>Updated "System Peripherals" on page 1-18, "HPS-FPGA AXI Bridges" on page 1-19, "HPS SDRAM Controller Subsystem" on page 1-19, "FPGA Configuration and Processor Booting" on page 1-19, and "Hardware and Software Development" on page 1-20.</li> <li>Minor text edits.</li> </ul>
October 2011	1.0	Initial release.